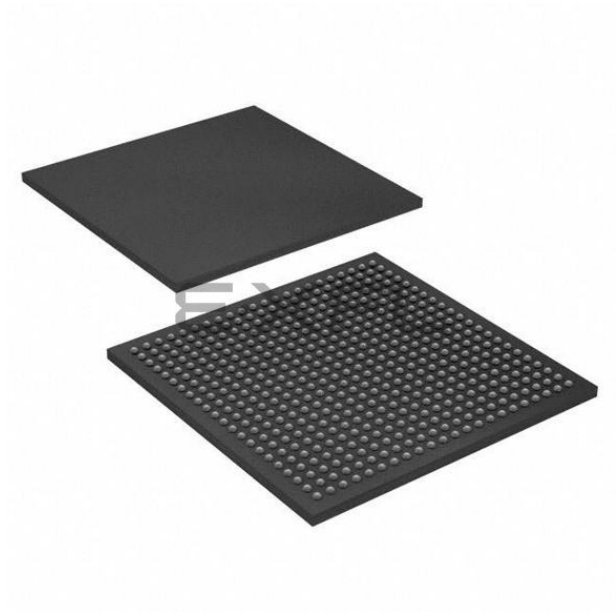

Welcome to E-XFL.COM

Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details	
Product Status	Active
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	925MHz
Primary Attributes	FPGA - 40K Logic Elements
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-FBGA
Supplier Device Package	484-UBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cseba4u19c6n

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Summary of Cyclone V Features

Table 2. Summary of Features for Cyclone V Devices

Feature	Description	
Technology	• TSMC's 28-nm low-power (28LP) process technology • 1.1 V core voltage	
Packaging	• Wirebond low-halogen packages • Multiple device densities with compatible package footprints for seamless migration between different device densities • RoHS-compliant and leaded(1) options	
High-performance FPGA fabric	Enhanced 8-input ALM with four registers	
Internal memory blocks	• M10K—10-kilobits (Kb) memory blocks with soft error correction code (ECC) • Memory logic array block (MLAB)—640-bit distributed LUTRAM where you can use up to 25% of the ALMs as MLAB memory	
Embedded Hard IP blocks	Variable-precision DSP	• Native support for up to three signal processing precision levels (three 9 x 9, two 18 x 18, or one 27 x 27 multiplier) in the same variable-precision DSP block • 64-bit accumulator and cascade • Embedded internal coefficient memory • Preadder/subtractor for improved efficiency
	Memory controller	DDR3, DDR2, and LPDDR2 with 16 and 32 bit ECC support
	Embedded transceiver I/O	PCI Express* (PCIe*) Gen2 and Gen1 (x1, x2, or x4) hard IP with multifunction support, endpoint, and root port
Clock networks	• Up to 550 MHz global clock network • Global, quadrant, and peripheral clock networks • Clock networks that are not used can be powered down to reduce dynamic power	
Phase-locked loops (PLLs)	• Precision clock synthesis, clock delay compensation, and zero delay buffering (ZDB) • Integer mode and fractional mode	
FPGA General-purpose I/Os (GPIOs)	• 875 megabits per second (Mbps) LVDS receiver and 840 Mbps LVDS transmitter • 400 MHz/800 Mbps external memory interface • On-chip termination (OCT) • 3.3 V support with up to 16 mA drive strength	
Low-power high-speed serial interface	• 614 Mbps to 6.144 Gbps integrated transceiver speed • Transmit pre-emphasis and receiver equalization • Dynamic partial reconfiguration of individual channels	
HPS (Cyclone V SE, SX, and ST devices only)	• Single or dual-core Arm Cortex-A9 MPCore processor-up to 925 MHz maximum frequency with support for symmetric and asymmetric multiprocessing • Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, controller area network (CAN), serial peripheral interface (SPI), I^2C interface, and up to 85 HPS GPIO interfaces • System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers • On-chip RAM and boot ROM	

continued...

(1) Contact Intel for availability.

Feature	Description
	• HPS–FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa • FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller • Arm CoreSight™ JTAG debug access port, trace port, and on-chip trace storage
Configuration	• Tamper protection—comprehensive design protection to protect your valuable IP investments • Enhanced advanced encryption standard (AES) design security features • CvP • Dynamic reconfiguration of the FPGA • Active serial (AS) x1 and x4, passive serial (PS), JTAG, and fast passive parallel (FPP) x8 and x16 configuration options • Internal scrubbing (2) • Partial reconfiguration (3)

Cyclone V Device Variants and Packages

Table 3. Device Variants for the Cyclone V Device Family

Variant	Description
Cyclone V E	Optimized for the lowest system cost and power requirement for a wide spectrum of general logic and DSP applications
Cyclone V GX	Optimized for the lowest cost and power requirement for 614 Mbps to 3.125 Gbps transceiver applications
Cyclone V GT	The FPGA industry's lowest cost and lowest power requirement for 6.144 Gbps transceiver applications
Cyclone V SE	SoC with integrated Arm-based HPS
Cyclone V SX	SoC with integrated Arm-based HPS and 3.125 Gbps transceivers
Cyclone V ST	SoC with integrated Arm-based HPS and 6.144 Gbps transceivers

Cyclone V E

This section provides the available options, maximum resource counts, and package plan for the Cyclone V E devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Product Selector Guide.

Related Information

Product Selector Guide
Provides the latest information about Intel products.

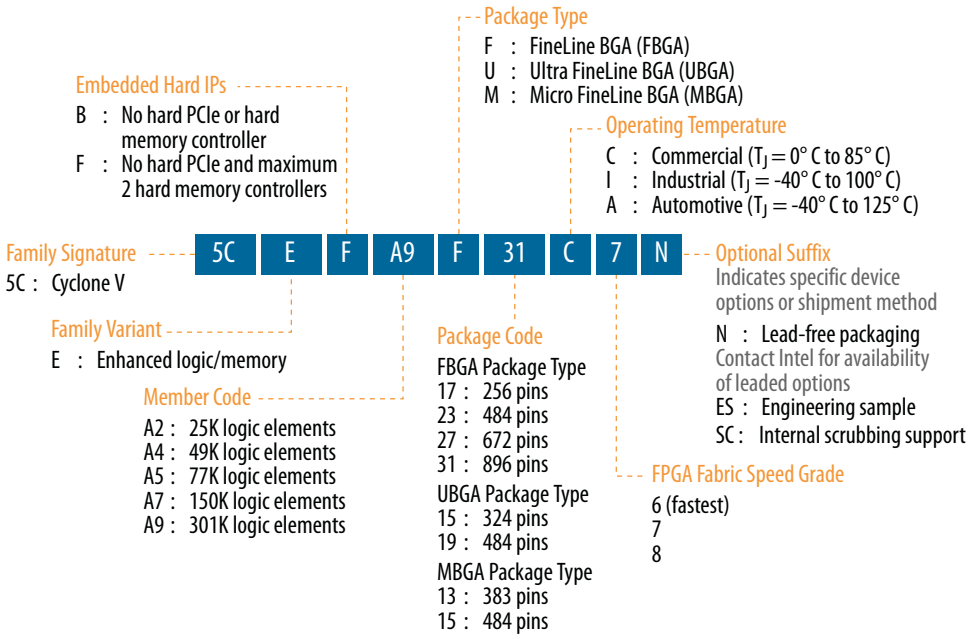
(2) The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

(3) The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel® sales representatives.

Available Options

Figure 1. Sample Ordering Code and Available Options for Cyclone V E Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



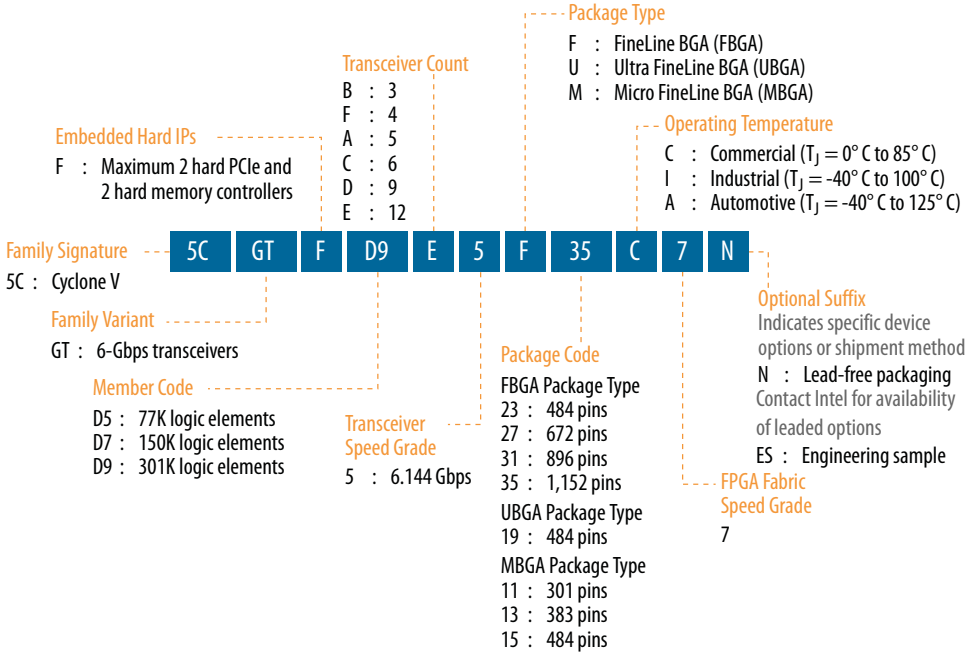
Maximum Resources

Table 4. Maximum Resource Counts for Cyclone V E Devices

Resource		Member Code				
		A2	A4	A5	A7	A9
Logic Elements (LE) (K)		25	49	77	150	301
ALM		9,430	18,480	29,080	56,480	113,560
Register		37,736	73,920	116,320	225,920	454,240
Memory (Kb)	M10K	1,760	3,080	4,460	6,860	12,200
	MLAB	196	303	424	836	1,717
Variable-precision DSP Block		25	66	150	156	342
18 x 18 Multiplier		50	132	300	312	684
PLL		4	4	6	7	8
GPIO		224	224	240	480	480
LVDS	Transmitter	56	56	60	120	120
	Receiver	56	56	60	120	120
Hard Memory Controller		1	1	2	2	2

Available Options

Figure 3. Sample Ordering Code and Available Options for Cyclone V GT Devices



Maximum Resources

Table 8. Maximum Resource Counts for Cyclone V GT Devices

Resource		Member Code		
		D5	D7	D9
Logic Elements (LE) (K)		77	150	301
ALM		29,080	56,480	113,560
Register		116,320	225,920	454,240
Memory (Kb)	M10K	4,460	6,860	12,200
	MLAB	424	836	1,717
Variable-precision DSP Block		150	156	342
18 x 18 Multiplier		300	312	684
PLL		6	7	8
6 Gbps Transceiver		6	9	12
GPIO(5)		336	480	560
LVDS	Transmitter	84	120	140

continued...

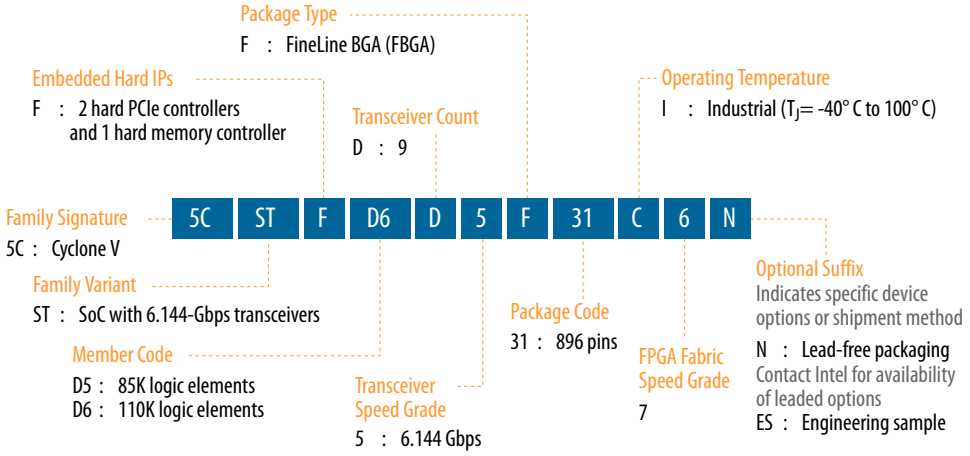
(5) The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Related Information

Product Selector Guide
Provides the latest information about Intel products.

Available Options

Figure 6. Sample Ordering Code and Available Options for Cyclone V ST Devices



Maximum Resources

Table 14. Maximum Resource Counts for Cyclone V ST Devices

Resource		Member Code	
		D5	D6
Logic Elements (LE) (K)		85	110
ALM		32,070	41,910
Register		128,300	166,036
Memory (Kb)	M10K	3,970	5,570
	MLAB	480	621
Variable-precision DSP Block		87	112
18 x 18 Multiplier		174	224
FPGA PLL		6	6
HPS PLL		3	3
6.144 Gbps Transceiver		9	9
FPGA GPIO(10)		288	288
HPS I/O		181	181
LVDS	Transmitter	72	72

continued...

(10) The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Resource		Member Code	
		D5	D6
	Receiver	72	72
PCIe Hard IP Block		2	2
FPGA Hard Memory Controller		1	1
HPS Hard Memory Controller		1	1
Arm Cortex-A9 MPCore Processor		Dual-core	Dual-core

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices
Provides the number of LVDS channels in each device package.

Package Plan

Table 15. Package Plan for Cyclone V ST Devices

- The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.
- Transceiver counts shown are for transceiver ≤5 Gbps . 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the *Cyclone V Device Handbook Volume 2: Transceivers*.

Member Code	F896 (31 mm)		
	FPGA GPIO	HPS I/O	XCVR
D5	288	181	9 (11)
D6	288	181	9 (11)

Related Information

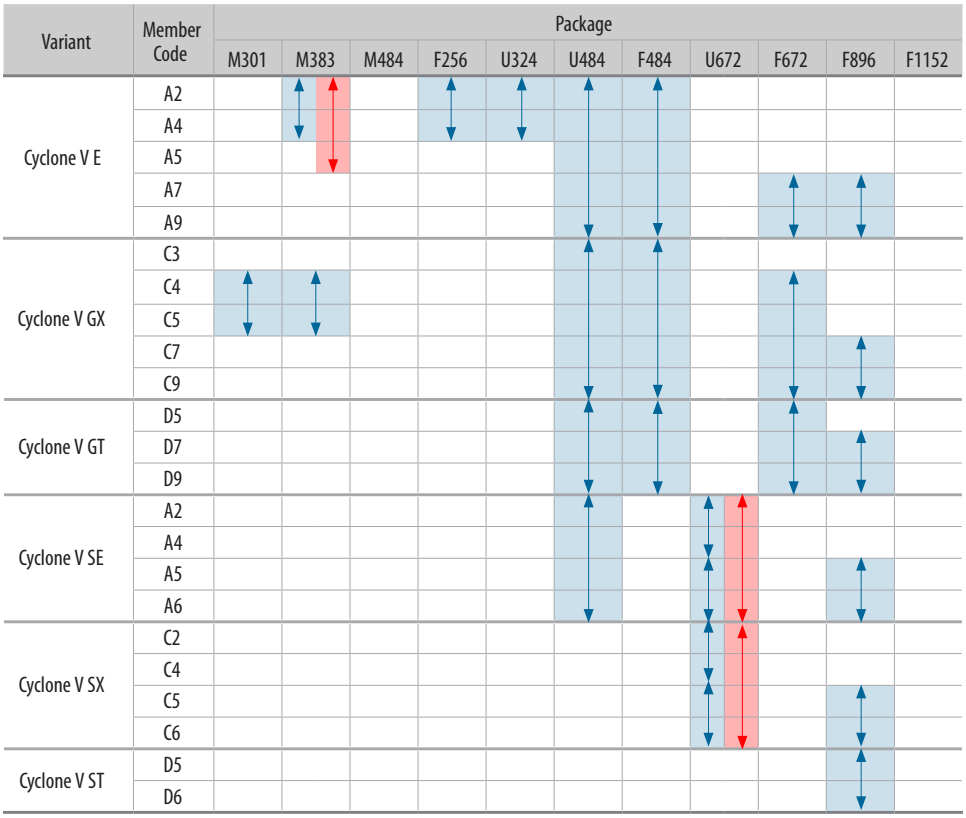
6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers
Provides more information about 6 Gbps transceiver channel count.

(11) If you require CPRI (at 4.9152 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to seven full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.

I/O Vertical Migration for Cyclone V Devices

Figure 7. Vertical Migration Capability Across Cyclone V Device Packages and Densities

The arrows indicate the vertical migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



You can achieve the vertical migration shaded in red if you use only up to 175 GPIOs for the M383 package, and 138 GPIOs for the U672 package. These migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

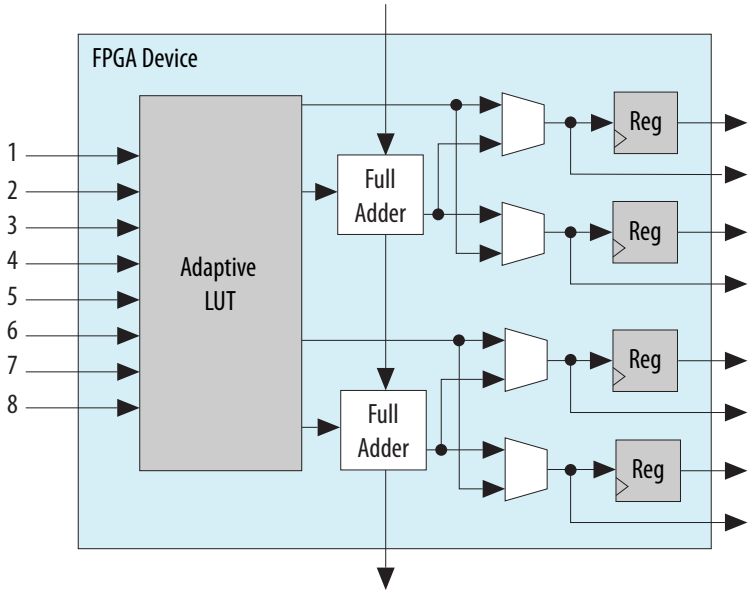
Note: To verify the pin migration compatibility, use the Pin Migration View window in the Intel Quartus Prime software Pin Planner.

Adaptive Logic Module

Cyclone V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.

Figure 8. ALM for Cyclone V Devices



You can configure up to 25% of the ALMs in the Cyclone V devices as distributed memory using MLABs.

Related Information

Embedded Memory Capacity in Cyclone V Devices on page 21
Lists the embedded memory capacity for each device.

Variable-Precision DSP Block

Cyclone V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18 and 27 x 27 bits natively
- A 64-bit accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Internal coefficient register banks, 8 deep, for each multiplier in 18- or 27-bit mode
- Fully independent multiplier operation
- A second accumulator feedback register to accommodate complex multiply-accumulate functions
- Fully independent Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Intel Quartus Prime design software

Variant	Member Code	Variable-precision DSP Block	Independent Input and Output Multiplications Operator			18 x 18 Multiplier Adder Mode	18 x 18 Multiplier Adder Summed with 36 bit Input
			9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier		
	C6	112	336	224	112	112	112
Cyclone V ST	D5	87	261	174	87	87	87
	D6	112	336	224	112	112	112

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.

Types of Embedded Memory

The Cyclone V devices contain two types of memory blocks:

- 10 Kb M10K blocks—blocks of dedicated memory resources. The M10K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Cyclone V devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

Embedded Memory Capacity in Cyclone V Devices

Table 18. Embedded Memory Capacity and Distribution in Cyclone V Devices

Variant	Member Code	M10K		MLAB		Total RAM Bit (Kb)
		Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	
Cyclone V E	A2	176	1,760	314	196	1,956
	A4	308	3,080	485	303	3,383
	A5	446	4,460	679	424	4,884
	A7	686	6,860	1338	836	7,696
	A9	1,220	12,200	2748	1,717	13,917
Cyclone V GX	C3	135	1,350	291	182	1,532
	C4	250	2,500	678	424	2,924
	C5	446	4,460	678	424	4,884
	C7	686	6,860	1338	836	7,696
	C9	1,220	12,200	2748	1,717	13,917

continued...

PLL Features

The PLLs in the Cyclone V devices support the following features:

- Frequency synthesis
- On-chip clock deskew
- Jitter attenuation
- Programmable output clock duty cycles
- PLL cascading
- Reference clock switchover
- Programmable bandwidth
- User-mode reconfiguration of PLLs
- Low power mode for each fractional PLL
- Dynamic phase shift
- Direct, source synchronous, zero delay buffer, external feedback, and LVDS compensation modes

Fractional PLL

In addition to integer PLLs, the Cyclone V devices use a fractional PLL architecture. The devices have up to eight PLLs, each with nine output counters. You can use the output counters to reduce PLL usage in two ways:

- Reduce the number of oscillators that are required on your board by using fractional PLLs
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

If you use the fractional PLL mode, you can use the PLLs for precision fractional-N frequency synthesis—removing the need for off-chip reference clock sources in your design.

The transceiver fractional PLLs that are not used by the transceiver I/Os can be used as general purpose fractional PLLs by the FPGA fabric.

FPGA General Purpose I/O

Cyclone V devices offer highly configurable GPIOs. The following list describes the features of the GPIOs:

- Programmable bus hold and weak pull-up
- LVDS output buffer with programmable differential output voltage (V_{OD}) and programmable pre-emphasis
- On-chip parallel termination (R_T OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture

External Memory Performance

Table 20. External Memory Interface Performance in Cyclone V Devices

The maximum and minimum operating frequencies depend on the memory interface standards and the supported delay-locked loop (DLL) frequency listed in the device datasheet.

Interface	Voltage (V)	Maximum Frequency (MHz)		Minimum Frequency (MHz)
		Hard Controller	Soft Controller	
DDR3 SDRAM	1.5	400	303	303
	1.35	400	303	303
DDR2 SDRAM	1.8	400	300	167
LPDDR2 SDRAM	1.2	333	300	167

Related Information

External Memory Interface Spec Estimator
For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

HPS External Memory Performance

Table 21. HPS External Memory Interface Performance

The hard processor system (HPS) is available in Cyclone V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	400
	1.35	400
DDR2 SDRAM	1.8	400
LPDDR2 SDRAM	1.2	333

Related Information

External Memory Interface Spec Estimator
For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

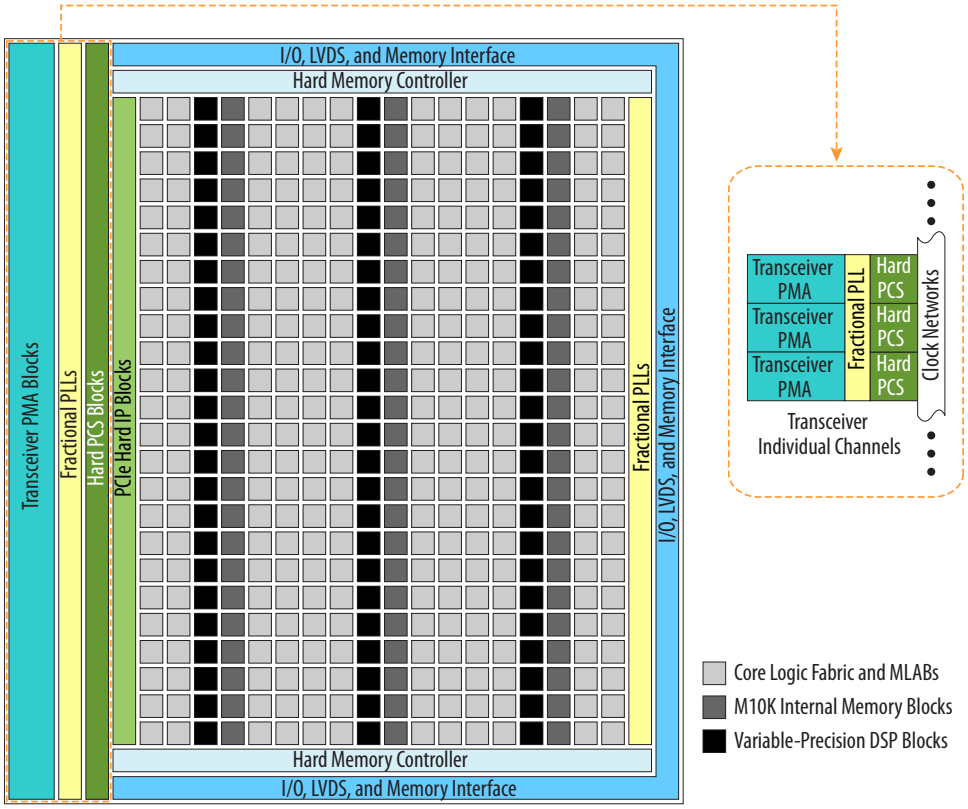
Cyclone V devices deliver the industry’s lowest power 6.144 Gbps transceivers at an estimated 88 mW maximum power consumption per channel. Cyclone V transceivers are designed to be compliant with a wide range of protocols and data rates.

Transceiver Channels

The transceivers are positioned on the left outer edge of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.

Figure 10. Device Chip Overview for Cyclone V GX and GT Devices

The figure shows a Cyclone V FPGA with transceivers. Different Cyclone V devices may have a different floorplans than the one shown here.



PMA Features

To prevent core and I/O noise from coupling into the transceivers, the PMA block is isolated from the rest of the chip—ensuring optimal signal integrity. For the transceivers, you can use the channel PLL of an unused receiver PMA as an additional transmit PLL.

Table 22. PMA Features of the Transceivers in Cyclone V Devices

Features	Capability
Backplane support	Driving capability up to 6.144 Gbps
PLL-based clock recovery	Superior jitter tolerance
Programmable deserialization and word alignment	Flexible deserialization width and configurable word alignment pattern
Equalization and pre-emphasis	• Up to 14.37 dB of pre-emphasis and up to 4.7 dB of equalization • No decision feedback equalizer (DFE)
Ring oscillator transmit PLLs	614 Mbps to 6.144 Gbps
Input reference clock range	20 MHz to 400 MHz
Transceiver dynamic reconfiguration	Allows the reconfiguration of a single channel without affecting the operation of other channels

PCS Features

The Cyclone V core logic connects to the PCS through an 8, 10, 16, 20, 32, or 40 bit interface, depending on the transceiver data rate and protocol. Cyclone V devices contain PCS hard IP to support PCIe Gen1 and Gen2, Gbps Ethernet (GbE), Serial RapidIO® (SRIO), and Common Public Radio Interface (CPRI).

Most of the standard and proprietary protocols from 614 Mbps to 6.144 Gbps are supported.

Table 23. Transceiver PCS Features for Cyclone V Devices

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
3-Gbps and 6-Gbps Basic	0.614 to 6.144	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • Transmitter bit-slip	• Word aligner • Deskew FIFO • Rate-match FIFO • 8B/10B decoder • Byte deserializer • Byte ordering • Receiver phase compensation FIFO
PCIe Gen1 (x1, x2, x4)	2.5 and 5.0	• Dedicated PCIe PHY IP core • PIPE 2.0 interface to the core logic	• Dedicated PCIe PHY IP core • PIPE 2.0 interface to the core logic
PCIe Gen2 (x1, x2, x4)(12)			
GbE	1.25	• Custom PHY IP core with preset feature • GbE transmitter synchronization state machine	• Custom PHY IP core with preset feature • GbE receiver synchronization state machine
XAUI (13)	3.125	• Dedicated XAUI PHY IP core • XAUI synchronization state machine for bonding four channels	• Dedicated XAUI PHY IP core • XAUI synchronization state machine for realigning four channels
HiGig	3.75		
SRIO 1.3 and 2.1	1.25 to 3.125	• Custom PHY IP core with preset feature • SRIO version 2.1-compliant x2 and x4 channel bonding	• Custom PHY IP core with preset feature • SRIO version 2.1-compliant x2 and x4 deskew state machine
SDI, SD/HD, and 3G-SDI	0.27(14), 1.485, and 2.97	Custom PHY IP core with preset feature	Custom PHY IP core with preset feature
JESD204A	0.3125(15) to 3.125		

continued...

(12) PCIe Gen2 is supported for Cyclone V GT and ST devices. The PCIe Gen2 x4 support is PCIe-compatible.

(13) XAUI is supported through the soft PCS.

(14) The 0.27-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

(15) The 0.3125-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
Serial ATA Gen1 and Gen2	1.5 and 3.0	• Custom PHY IP core with preset feature • Electrical idle	• Custom PHY IP core with preset feature • Signal detect • Wider spread of asynchronous SSC
CPRI 4.1(16)	0.6144 to 6.144	• Dedicated deterministic latency PHY IP core • Transmitter (TX) manual bit-slip mode	• Dedicated deterministic latency PHY IP core • Receiver (RX) deterministic latency state machine
OBSAI RP3	0.768 to 3.072		
V-by-One HS	Up to 3.75	Custom PHY IP core	• Custom PHY IP core • Wider spread of asynchronous SSC
DisplayPort 1.2(17)	1.62 and 2.7		

SoC with HPS

Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core Arm Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

(16) High-voltage output mode (1000-BASE-CX) is not supported.

(17) Pending characterization.

Note: Although the FPGA fabric and HPS are on separate power domains, the HPS must remain powered up during operation while the FPGA fabric can be powered up or down as required.

Related Information

Cyclone V Device Family Pin Connection Guidelines
Provides detailed information about power supply pin connection guidelines and power regulator sharing.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer (Standard) system integration tool in the Intel Quartus Prime software.

For software development, the Arm-based SoC devices inherit the rich software development ecosystem available for the Arm Cortex-A9 MPCore processor. The software development process for Intel SoCs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux, VxWorks®, and other operating systems is available for the SoCs. For more information on the operating systems support availability, contact the Intel sales team.

You can begin device-specific firmware and software development on the Intel SoC Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board that runs on a PC. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Related Information

International Altera Sales Support Offices

Dynamic and Partial Reconfiguration

The Cyclone V devices support dynamic reconfiguration and partial reconfiguration.

Dynamic Reconfiguration

The dynamic reconfiguration feature allows you to dynamically change the transceiver data rates, PMA settings, or protocols of a channel, without affecting data transfer on adjacent channels. This feature is ideal for applications that require on-the-fly multiprotocol or multirate support. You can reconfigure the PMA and PCS blocks with dynamic reconfiguration.

Partial Reconfiguration

Note: The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Partial reconfiguration allows you to reconfigure part of the device while other sections of the device remain operational. This capability is important in systems with critical uptime requirements because it allows you to make updates or adjust functionality without disrupting services.

Apart from lowering cost and power consumption, partial reconfiguration increases the effective logic density of the device because placing device functions that do not operate simultaneously is not necessary. Instead, you can store these functions in external memory and load them whenever the functions are required. This capability reduces the size of the device because it allows multiple applications on a single device—saving the board space and reducing the power consumption.

Intel simplifies the time-intensive task of partial reconfiguration by building this capability on top of the proven incremental compile and design flow in the Intel Quartus Prime design software. With the Intel solution, you do not need to know all the intricate device architecture details to perform a partial reconfiguration.

Partial reconfiguration is supported through the FPP x16 configuration interface. You can seamlessly use partial reconfiguration in tandem with dynamic reconfiguration to enable simultaneous partial reconfiguration of both the device core and transceivers.

Enhanced Configuration and Configuration via Protocol

Cyclone V devices support 1.8 V, 2.5 V, 3.0 V, and 3.3 V programming voltages and several configuration schemes.

Table 24. Configuration Schemes and Features Supported by Cyclone V Devices

Mode	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompression	Design Security	Partial Reconfiguration[18]	Remote System Update
AS through the EPCS and EPCQ serial configuration device	1 bit, 4 bits	100	—	Yes	Yes	—	Yes
PS through CPLD or external microcontroller	1 bit	125	125	Yes	Yes	—	—
FPP	8 bits	125	—	Yes	Yes	—	Parallel flash loader
	16 bits	125	—	Yes	Yes	Yes	
CvP (PCIe)	x1, x2, and x4 lanes	—	—	Yes	Yes	Yes	—
JTAG	1 bit	33	33	—	—	—	—

Instead of using an external flash or ROM, you can configure the Cyclone V devices through PCIe using CvP. The CvP mode offers the fastest configuration rate and flexibility with the easy-to-use PCIe hard IP block interface. The Cyclone V CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

Related Information

Configuration via Protocol (CvP) Implementation in Intel FPGAs User Guide
Provides more information about CvP.

(18) The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Power Management

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Cyclone V devices consume less power than previous generation Cyclone FPGAs:

- Total device core power consumption—less by up to 40%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Cyclone V devices contain several hard IP blocks that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.

Document Revision History for Cyclone V Device Overview

Document Version	Changes
2018.05.07	• Added the low power option ("L" suffix) for Cyclone V SE and Cyclone V SX devices in the *Sample Ordering Code and Available Options* diagrams. • Rebranded as Intel.

Date	Version	Changes
December 2017	2017.12.18	• Updated ALM resources for Cyclone V E, Cyclone V SE, Cyclone V SX, and Cyclone V ST devices.
June 2016	2016.06.10	Updated Cyclone V GT speed grade to –7 in Sample Ordering Code and Available Options for Cyclone V GT Devices diagram.
December 2015	2015.12.21	• Added descriptions to package plan tables for Cyclone V GT and ST devices. • Changed instances of *Quartus II* to *Quartus Prime*.
June 2015	2015.06.12	• Replaced a note to partial reconfiguration feature. Note: The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Altera sales representatives. • Updated logic elements (LE) (K) for the following devices: — Cyclone V E A7: Updated from 149.5 to 150 — Cyclone V GX C3: Updated from 35.5 to 36 — Cyclone V GX C7: Updated from 149.7 to 150 — Cyclone V GT D7: Updated from 149.5 to 150 • Updated MLAB (Kb) in Maximum Resource Counts for Cyclone V GX Devices table as follows: — Cyclone V GX C3: Updated from 291 to 182 — Cyclone V GX C4: Updated from 678 to 424 — Cyclone V GX C5: Updated from 678 to 424 — Cyclone V GX C7: Updated from 1,338 to 836 — Cyclone V GX C9: Updated from 2,748 to 1,717

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Date	Version	Changes
		• Updated MLAB RAM Bit (Kb) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: — Cyclone V GX C3: Updated from 181 to 182 — Cyclone V GX C4: Updated from 295 to 424 • Updated Total RAM Bit (Kb) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: — Cyclone V GX C3: Updated from 1,531 to 1,532 — Cyclone V GX C4: Updated from 2,795 to 2,924 • Updated MLAB Block count in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: — Cyclone V GX C4: Updated from 472 to 678 — Cyclone V GX C5: Updated from 679 to 678
March 2015	2015.03.31	• Added internal scrubbing feature under configuration in Summary of Features for Cyclone V Devices table. • Added optional suffix "SC: Internal scrubbing support" to the following diagrams: — Sample Ordering Code and Available Options for Cyclone V E Devices — Sample Ordering Code and Available Options for Cyclone V GX Devices — Sample Ordering Code and Available Options for Cyclone V SE Devices — Sample Ordering Code and Available Options for Cyclone V SX Devices
January 2015	2015.01.23	• Updated Sample Ordering Code and Available Options for Cyclone V ST Devices figure because Cyclone V ST devices are only available in I temperature grade and –7 speed grade. — Operating Temperature: Removed C and A temperature grades — FPGA Fabric Speed Grade: Removed –6 and –8 speed grades • Updated the transceiver specification for Cyclone V ST from 5 Gbps to 6.144 Gbps: — Device Variants for the Cyclone V Device Family table — Sample Ordering Code and Available Options for Cyclone V ST Devices figure — Maximum Resource Counts for Cyclone V ST Devices • Updated Maximum Resource Counts for Cyclone V GX Devices table for Cyclone V GX G3 devices. — Logic elements (LE) (K): Updated from 35.7 to 35.5 — Variable-precision DSP block: Updated from 51 to 57 — 18 x 18 multiplier: Updated from 102 to 114 • Updated Number of Multipliers in Cyclone V Devices table for Cyclone V GX G3 devices. — Variableprecision DSP Block: Updated from 51 to 57 — 9 x 9 Multiplier: Updated from 153 to 171 — 18 x 18 Multiplier: Updated from 102 to 114 — 27 x 27 Multiplier: Updated from 51 to 57 — 18 x 18 Multiplier Adder Mode: Updated from 51 to 57 — 18 x 18 Multiplier Adder Summed with 36 bit Input: Updated from 51 to 57 • Updated Embedded Memory Capacity and Distribution in Cyclone V Devices table for Cyclone V GX G3 devices. — M10K block: Updated from 119 to 135 — M10K RAM bit (Kb): Updated from 1,190 to 1,350 — MLAB block: Updated from 255 to 291 — MLAB RAM bit (Kb): Updated from 159 to 181 — Total RAM bit (Kb): Updated from 1,349 to 1,531
October 2014	2014.10.06	Added a footnote to the "Transceiver PCS Features for Cyclone V Devices" table to show that PCIe Gen2 is supported for Cyclone V GT and ST devices.

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Date	Version	Changes
		• Updated Figure 1, Figure 2, Figure 3, Figure 4, Figure 5, Figure 6, and Figure 10. • Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections. • Text edits throughout the document.
February 2012	1.2	• Updated Table 1–2, Table 1–3, and Table 1–6. • Updated "Cyclone V Family Plan" on page 1–4 and "Clock Networks and PLL Clock Sources" on page 1–15. • Updated Figure 1–1 and Figure 1–6.
November 2011	1.1	• Updated Table 1–1, Table 1–2, Table 1–3, Table 1–4, Table 1–5, and Table 1–6. • Updated Figure 1–4, Figure 1–5, Figure 1–6, Figure 1–7, and Figure 1–8. • Updated "System Peripherals" on page 1–18, "HPS–FPGA AXI Bridges" on page 1–19, "HPS SDRAM Controller Subsystem" on page 1–19, "FPGA Configuration and Processor Booting" on page 1–19, and "Hardware and Software Development" on page 1–20. • Minor text edits.
October 2011	1.0	Initial release.